



Initial Product/Process Change Notification

Document #: IPCN25729ZA

Issue Date: 03 May 2024

Title of Change:	Wafer Fab Site Addition of onsemi, Bucheon Korea as alternate fab site for ESD and Surge Protection products	
Proposed Changed Material First Ship Date:	30 Jun 2025 or earlier if approved by customer	
Current Material Last Order Date:	N/A <i>Orders received after the Current Material Last Order Date expiration are to be considered as orders for new changed material as described in this PCN. Orders for current (unchanged) material after this date will be per mutual agreement and current material inventory availability.</i>	
Current Material Last Delivery Date:	N/A <i>The Current Material Last Delivery Date may be subject to change based on build and depletion of the current (unchanged) material inventory.</i>	
Product Category:	Active components – Discrete components	
Contact information:	Contact your local onsemi Sales Office or norhayati.othman@onsemi.com	
PCN Samples Contact:	Contact your local onsemi Sales Office to place sample order. Sample requests are to be submitted no later than 45 days after publication of this change notification. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.	
Additional Reliability Data:	Contact your local onsemi Sales Office or Nicky.Siu@onsemi.com	
Type of Notification:	This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 6 months prior to implementation of the change. In case of questions, contact < PCN.Support@onsemi.com >.	
Change Category		
Category	Type of Change	
Process - Wafer Production	Move of all or part of wafer fab to a different location/site/subcontractor	
Equipment	Production from a new equipment/tool which uses the same basic technology (replacement equipment or extension of existing equipment pool) without change of process.	
Description and Purpose:		
This IPCN announces the qualification of onsemi, Bucheon Korea as additional wafer fab for ESD and Surge Protection products.		
	Before Change Description	After Change Description
Wafer Fab	LA Semiconductor, Idaho, United States	onsemi Bucheon, Korea, LA Semiconductor, Idaho, United States
Reason / Motivation for Change:		
Source/Supply/Capacity Changes		
Anticipated impact on fit, form, function, reliability, product safety or manufacturability:	The device will be qualified and validated based on the same Product Specification. No anticipated impacts.	



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Sites Affected:

onsemi Sites

onsemi Bucheon, Korea

External Foundry/Subcon Sites

None

Marking of Parts/ Traceability of Change:

Changed material can be identified by lot code

Qualification Plan:

Qualification tests are designed to show that the reliability of the transferred devices will continue to meet or exceed onsemi standard.

QV DEVICE NAME: ESD7321MUT5G

RMS: S94408

PACKAGE: X3DFN

Test	Specification	Condition	Interval
High Temperature Reverse Bias	JESD22-A108	Ta=150°C, 100% max rated V	1008 hrs
High Temperature Storage Life	JESD22-A103	Ta=150°C	1008 hrs
Preconditioning	J-STD-020 JESD-A113	MSL 1@260°C	
Temperature Cycling	JESD22-A104	Ta= -55°C to +150°C	1000 cyc
Highly Accelerated Stress Test	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs

QV DEVICE NAME: ESD9M5.0ST5G

RMS: 97093

PACKAGE: SOD923

Test	Specification	Condition	Interval
High Temperature Reverse Bias	JESD22-A108	Ta=150°C, 100% max rated V	1008 hrs
High Temperature Storage Life	JESD22-A103	Ta=150°C	2016 hrs
Preconditioning	J-STD-020 JESD-A113	MSL 1 @260°C	
Temperature Cycling	JESD22-A104	Ta= -55°C to +150°C	1000 cyc
Highly Accelerated Stress Test	JESD22-A110	130°C, 85% RH, 18.8psig, bias	192 hrs
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs

QV DEVICE NAME: ESD8011MUT5G

RMS: 97108

PACKAGE: X3DFN

Test	Specification	Condition	Interval
High Temperature Reverse Bias	JESD22-A108	Ta=150°C, 100% max rated V	1008 hrs
Preconditioning	J-STD-020 JESD-A113	MSL 1 @260°C	
Highly Accelerated Stress Test	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs

QV DEVICE NAME: SZTVS4201MR6T1G

RMS: 97122

PACKAGE: TSOP6

Test	Specification	Condition	Interval
High Temperature Reverse Bias	JESD22-A108	Ta=150°C, 100% max rated V	1008 hrs
High Temperature Storage Life	JESD22-A103	Ta=150°C	2016 hrs
Preconditioning	J-STD-020 JESD-A113	MSL 1 @260°C	
Temperature Cycling	JESD22-A104	Ta= -55°C to +150°C	1000 cyc
Highly Accelerated Stress Test	JESD22-A110	130°C, 85% RH, 18.8psig, bias	192 hrs
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs

QV DEVICE NAME: SZESD7205DT5G

RMS: TBD

PACKAGE: SOT723

Test	Specification	Condition	Interval
High Temperature Reverse Bias	JESD22-A108	Ta=150°C, 100% max rated V	1008 hrs
High Temperature Storage Life	JESD22-A103	Ta=150°C	2016 hrs
Preconditioning	J-STD-020 JESD-A113	MSL 1@260°C	
Temperature Cycling	JESD22-A104	Ta= -55°C to +150°C	1000 cyc
Highly Accelerated Stress Test	JESD22-A110	130°C, 85% RH, 18.8psig, bias	192 hrs
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs

QV DEVICE NAME: SZESD7205WTT1G

RMS: TBD

PACKAGE: SC70

Test	Specification	Condition	Interval
High Temperature Reverse Bias	JESD22-A108	Ta=150°C, 100% max rated V	1008 hrs
High Temperature Storage Life	JESD22-A103	Ta=150°C	2016 hrs
Preconditioning	J-STD-020 JESD-A113	MSL 1@260°C	
Temperature Cycling	JESD22-A104	Ta= -55°C to +150°C	1000 cyc
Highly Accelerated Stress Test	JESD22-A110	130°C, 85% RH, 18.8psig, bias	192 hrs
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs

Estimated date for qualification completion: 28 January 2025

Electrical Characteristics Summary:

Electrical characteristics are not impacted.

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [PCN Customized Portal](#).

Current Part Number	New Part Number	Qualification Vehicle
SZESD8472MUT5G	#NONE	ESD7321MUT5G
SESD9L5.0ST5G	#NONE	ESD9M5, 0ST5G
SZESD9M5.0ST5G	#NONE	ESD9M5, 0ST5G
SZESD9R3.3ST5G	#NONE	ESD9M5, 0ST5G
SZESD8011MUT5G	#NONE	ESD8011MUT5G, ESD7321MUT5G
SZESD8351MUT5G	#NONE	ESD8011MUT5G, ESD7321MUT5G
SZNSP4201MR6T1G	#NONE	SZTVS4201MR6T1G
SZNSP2201MR6T1G	#NONE	SZTVS4201MR6T1G
SZTVS4201MR6T1G	#NONE	SZTVS4201MR6T1G
SZESD7205DT5G	#NONE	SZESD7205DT5G
SZESD7481MUT5G	#NONE	ESD7321MUT5G
SZESD7205WTT1G	#NONE	SZESD7205WTT1G

Appendix A: Changed Products

PCN#: IPCN25729ZA
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DIKG: DIGI-KEY

Product	Customer Part Number	Qualification Vehicle	New Part Number	Replacement Supplier
SZESD8472MUT5G		ESD7321MUT5G	#NONE	
SZESD9M5.0ST5G		ESD9M5, 0ST5G	#NONE	
SZESD9R3.3ST5G		ESD9M5, 0ST5G	#NONE	
SZNSP4201MR6T1G		SZTVS4201MR6T1G	#NONE	
SZNSP2201MR6T1G		SZTVS4201MR6T1G	#NONE	
SZTVS4201MR6T1G		SZTVS4201MR6T1G	#NONE	
SZESD7205DT5G		SZESD7205DT5G	#NONE	
SZESD7481MUT5G		ESD7321MUT5G	#NONE	
SZESD7205WTT1G		SZESD7205WTT1G	#NONE	
SESD9L5.0ST5G		ESD9M5, 0ST5G	#NONE	